

Thermal RC network (Foster)

SPICE thermal model

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
₹ _{th(j-mb)}	thermal resistance from junction to mounting base		-	-	0.51	K/W
	Cth ₁	2.085E-04 F		Ą	t:	
	Cth ₂	1.582E-03 F		_ 	tj	
	Cth ₃	1.124E-03 F			┎─┿──┐	
	Cth ₄	4.066E-03 F				1
	Cth ₅	1.379E-02 F		L	,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	1
	Cth ₆	2.696E-02 F				
	Cth ₇	6.892E-01 F		r		
	Cth ₈	1.806E+02 F			$\int Rth_2 + Cth_2$	2
	Rth₁	4.200Ε-04 Ω				
	Rth ₂	8.136E-04 Ω		Г	-	
	Rth ₃	9.132E-03 Ω			Rth3 = Cth;	3
	Rth ₄	2.352E-02 Ω		L	᠊᠋	
	Rth₅	8.209E-02 Ω			_	
	Rth ₆	3.277E-01 Ω				4
	Rth ₇	7.932E-02 Ω				Ŧ
	Rth ₈	8.874E-04 Ω	((P)		
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Part:	BUK752R3-40E			 		
Date:	17/4/2013			[3
Nodel Rth	0.52 K/W					
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